



PLCC

Plastic Leaded Chip Carrier Package

DESCRIPTION

Lingsen PLCC is a quad-sided, lead frame based plastic package. It is widely used for consumer products. Lingsen provides PLCC with 32L and 44L two lead counts.

The package meets JEDEC Moisture Sensitivity Level 3 standard that ensures reliability in its functions.

SPECIFICATIONS

• Die Thickness	726um (30mils) maximum
• Gold Wire	99.99% Au
• Mold Compound	EME G600 (Green) EME 6600CSP (Non-Green)
• Plating	Matte Tin
• Marking	White Ink / Laser Mark
• Packing	Antistatic Tube

APPLICATIONS

- Consumer Products
- Copiers, Printers, Scanners,
- Computers, Monitors and etc.
- Memory ICs

RELIABILITY

MSL Level: MSL 3 @ 240°C for Sn/Pb
 MSL Level: MSL 3 @ 260°C for Pb-Free & Green
 Pressure Cook Test: 168hrs (121°C, 100%RH, 2atm)
 Temperature Cycling: 1000cycles (-65°C/+150°C)
 HAST: 100hrs (130°C, 85%RH)
 Temperature & Humidity Test: 1,000hrs (85°C, 85%RH)
 High Temperature Storage: 1,000hrs (150°C)

FEATURES

- Available pin count: 32L & 44L
- "J" ead format
- Broad selection of die pad sizes
- JEDEC standard compliant
- JEDEC MSL level 3 qualified for all pin counts

THERMAL PERFORMANCE

Package	Body Size (mm)	Pad Size (mm)	Die Size (mm)	Thermal Performance θ_{ja} (°C/W)
PLCC 32L	11.43x13.97	8.636x7.62	7.847x6.452	26.58
PLCC 44L	16.54x16.54	6.35x6.35	5.029x5.08	29.19

Note: Simulated with JEDEC Standard 4-layer test board under still air condition, ambient temperature 45°C

ELECTRICAL PERFORMANCE

Package	Body Size (mm)	Pad Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)
PLCC 32L	11.43x13.97	8.636x7.62	100	1.377~5.910	0.864~5.477	7.058~359.3
PLCC 44L	16.54x16.54	6.35x6.35	100	2.993~6.878	1.219~1.470	20.57~241.6

Note: Results are simulated. Data is available through 2.5GHz.

CROSS-SECTION

